

The important questions



1. About length of substrate that can be cut

FU-100	FU-200	FU-300	FU-400	FU-500
100mm	200mm	300mm	400mm	500mm

2. About thickness of substrate that can be cut by the wheel cutter

Carbide Wheel	for ultra-thin substrate(CU)	for thin substrate(CT)	for standard substrate(CN)	Laser (CL)
Type	Normal	Normal	Normal	High penetrating
Thickness	0.15~0.5mm	0.5~1.3mm	1.1~3.0mm	0.05~2.0mm

Diamond Wheel	for ultra-thin substrate(DU)	for thin substrate(DT)	for standard substrate(DN)	Laser (DL)
Type	Normal	Normal	Normal	High penetrating
Thickness	0.15~0.5mm	0.5~1.3mm	1.1~3.0mm	0.05~2.0mm

3. About replace the wheel cutter

We recommend replace it becomes dull.

4. About typical material that can be cut by the wheel cutter

Material	Wheel cutter
Soda-lime glass/Silicon	Carbide Wheel Diamond Wheel(long lasting)
Sapphire/SiC/GaN (hard)	Diamond Wheel

5. About the magnetic substrate guide

- We recommend using two magnetic substrate guides to hold the substrate from both sides.
- When cutting wafers, please use the long type (MGL or MGU).
- They are not included with the precision glass cutter.

